ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INDUSTRIES®	ekburn, Illinois, A	Il rights reserved un ntions.	der both le	his docume evel parts, t	ent is a declaration	ion of the sencompasse	ubstance es all low	s within the manufactur er level materials for w	rer listed it hich the m	em. Note: if	f the item is an as has engineering	ssembly with lower responsibility.
IPC Web Site for Information of http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Ty			<ul> <li>Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia</li> </ul>				als and Mfg Information				
Supplier Information												
Company name* Company unique ID				Unique ID Authority					Response Date*			
semi									2024-04-25			
Contact Name	tet Name Title - Contact			]	Phone - Contact*				Email - Contact*			
duct-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr It	em Number	Mfr Item Name			Effective Date	e Version		Manufacturing Site		Weight*	UOM	Unit Type
LC75	C75760UJA-AH 12CH CONTANT C DRIVER		CURRENT LEI	)	2024-04-25		РНМ		-	100.67	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Plating / Grid Array Material Terminal Base Alloy J-		STD-020 MSL H	Rating	Peak Pro	ess Body 7	Temperatu	are Max Time at Peak	Temperat	ure Numb	er of Reflow Cy	cles
contains Bi CU Alloy 3				260		С	30	secon	ds 3			
Comments												
ATTENTION: MSL 3 Rated item requires Bake and	l Dry Pack (after	electrical test)										
For more information regarding material composition	on please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.26	mg	Supplier	Silicon (Si)	7440-21-3		4.2285	mg
			Supplier	Polyimide	Proprietary Data		0.0315	mg
Die Attach	0.38	mg	Supplier	Silver (Ag)	7440-22-4		0.2698	mg
			Supplier	Epoxy resins	129915-35-1		0.1102	mg
Lead Frame	34.81	mg	Supplier	Silver (Ag)	7440-22-4		0.369	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0418	mg
			Supplier	Iron (Fe)	7439-89-6		0.8111	mg
			Supplier	Copper (Cu)	7440-50-8		33.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0278	mg
Mold Compound-Black	59.22	mg		Epoxy Phenol Resin	proprietary data		7.1064	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2369	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		50.1001	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.7766	mg
Plating	1.71	mg	В	Bismuth (Bi)	7440-69-9		0.0103	mg
			Supplier	Tin (Sn)	7440-31-5		1.6997	mg
Wire Bond - Au	0.29	mg	Supplier	Gold (Au)	7440-57-5		0.29	mg